

ORMECON CSN

Immersion Tin

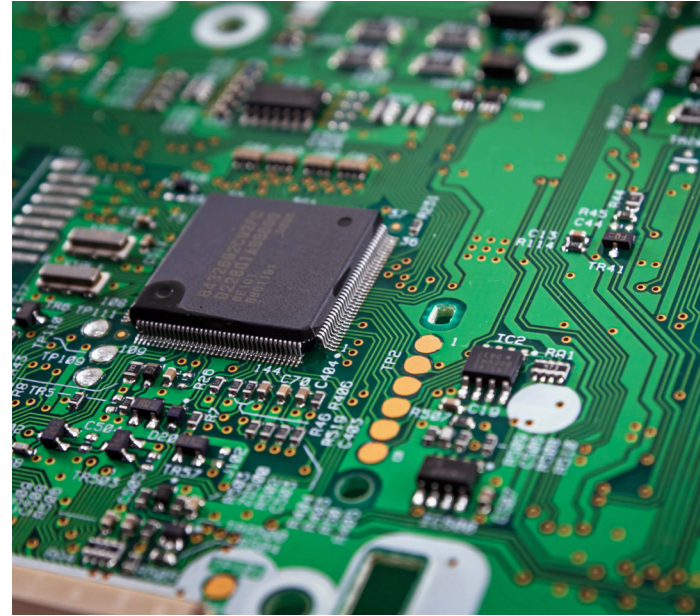
Trusted Reliability for When it Counts the Most

ORMECON CSN is a series of extremely stable immersion tin processes. Based on a patented predip, the ORMECON CSN tin processes offer exceptional solderability and appearance, even after multiple lead-free assembly reflows. The process utilizes a nanometal layer that is deposited by the ORMECON predip, which catalyzes the tin deposition before the immersion tin coating is applied. The resulting large tin grain structure significantly slows copper-tin intermetallic diffusion and is highly resistant to oxidation.

The Dolphin Immersion Tin process upgrade to ORMECON CSN provides reduced machine footprint for new lines while offering reduced downtime and easier maintenance. Dolphin also boosts throughput for existing lines and increases the maximum tin thickness for increased reliability with improved productivity.

KEY FEATURES

- Production-proven industry leading automotive final finish
- Patented predip reduces copper-tin diffusion up to 65%
- Dolphin upgrade eliminates chemical breakdown impurities while providing a uniform deposit
- Tolerates multiple lead-free assembly reflows
- Longest shelf life in the industry
- Unique crystal structure resists whisker formation

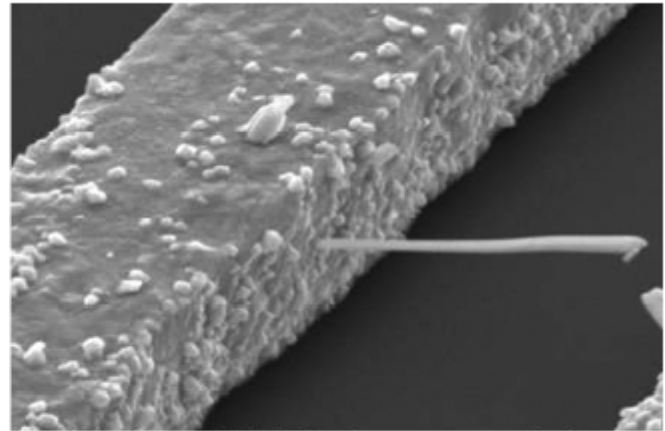
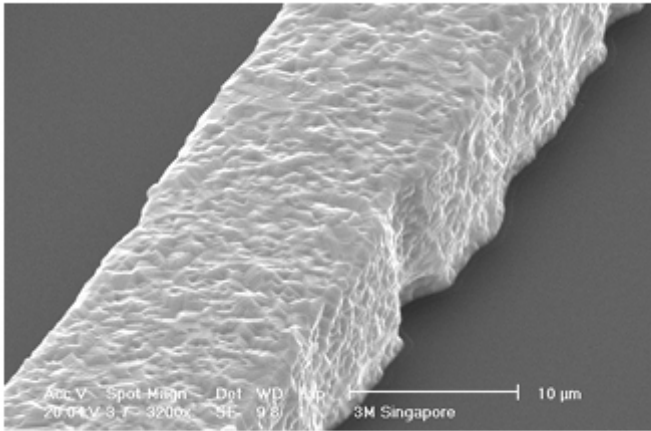


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The Competition Simply Can't Compete with ORMECON CSN

ORMECON CSN's patented predip provides a mild barrier to diffusion of copper into the tin while also creating a unique low-stress grain structure which greatly reduces whisker formation.



ORMECON CSN's formulation prevents tin whisker formation and provides superior solderability.

Competitive tin process with solderability and whisker problems.

Higher Thickness Capability with Dolphin

